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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/938,106	08/23/2001	James M. Derderian	4832US (01-0104)	1038
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TRASK BRITT P.O. BOX 2550 SALT LAKE CITY, UT 84110			EXAMINER IM, JUNGHWA M	
			ART UNIT	PAPER NUMBER
			2811	

DATE MAILED: 11/06/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary

Application No.

09/938,106

Applicant(s)

DERDERIAN, JAMES M.

Examiner

Junghwa M. Im

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-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 11 August 2003.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 23-27, 29-51 and 53-64 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 23-27, 29-51 and 53-64 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
- Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
- 11) ☐ The proposed drawing correction filed on _____ is: a) ☐ approved b) ☐ disapproved by the Examiner.
- If approved, corrected drawings are required in reply to this Office action.
- 12) ☐ The oath or declaration is objected to by the Examiner.

Priority under 35 U.S.C. §§ 119 and 120

- 13) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
 2. ☐ Certified copies of the priority documents have been received in Application No. _____.
 3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- * See the attached detailed Office action for a list of the certified copies not received.
- 14) ☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).
- a) ☐ The translation of the foreign language provisional application has been received.
- 15) ☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.

Attachment(s)

- | | |
|--|---|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413) Paper No(s). _____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | 5) <input type="checkbox"/> Notice of Informal Patent Application (PTO-152) |
| 3) <input type="checkbox"/> Information Disclosure Statement(s) (PTO-1449) Paper No(s) _____ | 6) <input type="checkbox"/> Other: _____ |

DETAILED ACTION

Claim Rejections - 35 USC § 112

The following is a quotation of the second paragraph of 35 U.S.C. 112:

The specification shall conclude with one or more claims particularly pointing out and distinctly claiming the subject matter which the applicant regards as his invention.

Claims 23 and 45 are rejected under 35 U.S.C. 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which applicant regards as the invention.

Claims 23 and 45 recites "...a back side of said semiconductor device ... and being *stably* supported thereby." The Application does not disclose the back side of the semiconductor device is *stably* supported by the discrete conductive elements. At best, the specification recites that the second semiconductor is positioned over the first semiconductor, resting on the top portions of discrete conductive elements in paragraph [0054]. Additionally, paragraph [0054] further recites that an adhesive material *secures* back side of the second semiconductor to an active surface of the first semiconductor material. And the Application supports this aspect in the respective portions of the specification such as in paragraph [0021] and [0024].

Claim 45 recites the limitation of "positioning a *second semiconductor device*..." There is insufficient antecedent basis for this limitation in the claim.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

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(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

Claims 23, 24, 29, 30, 33, 40, 45, 46, 49, 50, 53, 59 and 61-64 are rejected under 35 U.S.C. 103(a) as being unpatentable over Wu et al. (US 6,545,365), hereafter Wu.

Regarding claims 23 and 45, insofar as understood, Fig. 4 of Wu shows a device to use a method for assembling semiconductor devices with a densely stacked arrangement (col.2, line 64 through col. 3, line 61), comprising; a first semiconductor device 28; discrete conductive elements 32 over portions of said first semiconductor device; positioning a second semiconductor device 34 over the first semiconductor device and contacting at least some of said discrete conductive element said back side (col.3, lines 54-55) and said at least some of discrete conductive elements being electrically isolated from each other (col.3, lines 54-56).

Wu discloses substantially the entire claimed method to make substantially an identical device recited in the pending claim except the limitation of "a back side of said second semiconductor device ... being stably supported thereby." However, it would be obvious that the discrete conductive elements (the wires) contributes to support the back side of the second semiconductor device since the wires are in the direct contact beneath the back side of the second semiconductor device.

Regarding the limitation in the preamble of claim 45, Fig. 4 of Wu shows "semiconductor device in a stacked arrangement with stacked arrangement having a height substantially equal to combined thickness of each of the semiconductor device and distances discrete conductive elements associated therewith protrude above said each of the semiconductor devices." Also note that the limitation in the preamble does not have

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patentable weight because it has been held that a preamble is denied the effect of a limitation where the claim is drawn to a structure and the portion of the claim following the preamble is a self-contained description of the structure not depending for completeness upon the introductory clause. *Kropa v. Robie*, 88 USPQ 478 (CCPA 1951).

Regarding claims 24 and 46, Wu discloses positioning the second semiconductor device comprises positioning the second semiconductor device on said at least some of discrete conductive elements with the back side and the discrete conductive elements in mutual electrical isolation (col.3, lines 54-56).

Regarding claims 29 and 49, Wu discloses a quantity of adhesive material 50 to at least an active surface of the first semiconductor device (col.3, lines 24-25).

Regarding claims 30 and 50, it would be obvious that the device of Wu shows drawing the second semiconductor device toward the first semiconductor device after applying the adhesive on the first device since the adhesive is applied on the active surface of the first semiconductor device and positioning the second semiconductor device is followed.

Regarding claims 33 and 53, it would be obvious that the applying is effected after the positioning the second semiconductor device since positioning the second semiconductor device has to be done before permanent adhering to the first semiconductor device.

Regarding claims 40 and 59, Wu discloses securing the first semiconductor device and a substrate to one another (col.3, lines 16-20).

Regarding claim 61, it would be obvious that electrical communication would be established between bond pads of the second semiconductor device (34) and the

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corresponding contact areas of the substrate (col. 3, lines 41-43) in order to have the device operate functionally.

Regarding claim 62, Fig. 4 of Wu shows establishing communication comprises placing additional discrete conductive elements (56; wires) between each of the bond pads and the corresponding contact area of the corresponding contact areas.

Regarding claim 63, Fig. 4 of Wu shows providing at least one connective elements (42; signal output terminal) in communication with at least one bond pad of each of said first and second semiconductor devices (col. 3, lines 4-8).

Regarding claim 64, Wu discloses a method further comprising encapsulating (58 in Fig. 4; a packaging layer) said first and second semiconductor devices (col. 3, lines 44-47).

Claims 25, 26, 31, 34, 35, 41-44, 47, 51, 54-58 and 60 are rejected under 35 U.S.C. 103(a) as being unpatentable under obviousness over Wu in view of Lee et al. (US 6,388,313), hereafter Lee.

Regarding claims 25 and 47, Wu discloses the most aspect of the instant invention except "providing a dielectric coating on at least portion of said discrete conductive elements." Lee discloses a method providing a dielectric coating on at least portion of said discrete conductive elements (col. 5, lines 40-44). It would have been obvious to one of ordinary skill in the art at the time of the invention to apply a coat on the discrete conductive elements (wires) of Wu's device with the teaching of Lee in order to prevent a short circuit between the semiconductor device and the bare wires.

Regarding claim 26, Lee shows a method wherein the providing comprises

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forming at least one of a dielectric oxide and a dielectric polymer coating on at least said portions of the discrete conductive elements (col. 5, lines 22-24).

Regarding claims 31 and 51, Wu does not disclose "said drawing is effected by at least one of capillary action of the adhesive material, curing of the adhesive material, application of heat to the adhesive material, and vibration of the adhesive material." However, it would be obvious that such drawing is effected by one of the effects recited by the pending claim since Wu's adhesive material (resin) is identical to the one recited in the instant invention. Furthermore, Lee discloses the drawing is effected by at least curing of the adhesive material (resin) and application of heat to the adhesive material (col. 5, lines 32-40).

The limitations regarding claims 34 and 35 have been discussed in claims 30 and 31 with the combined teaching of Wu and Lee.

Regarding claim 41, Wu does not disclose "said placing the discrete conductive elements comprises securing the discrete conductive elements to contact areas of the substrate and the bond pads of the first semiconductor device." Lee shows a method wherein the placing the discrete conductive elements comprises securing the discrete conductive elements to contact areas of the substrate and the bond pads of the first semiconductor device (col. 5, lines 8-10). It would have been obvious to one of ordinary skill in the art at the time of the invention to incorporate the teaching of Lee into the device of Wu in order to have signals transferred between the stacked devices through having the discrete conductive elements (wires) secured on the contact areas (bond pads) on the substrate.

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Regarding claim 42, Lee shows the securing comprises electrically connecting bond pads of the second semiconductor device to the corresponding contacts areas of the substrate (col. 5, lines 13-16).

Regarding claim 43, Lee shows encapsulating at least portion of at least one of the substrate, the first semiconductor device, and the second semiconductor device (col. 6, lines 32-36).

Regarding claim 44, Lee shows forming external conductive elements 27 in Fig. 1 on the substrate in electrical communication with corresponding contact areas (col. 5, lines 1-4).

Limitations of claims 54 and 55 have been discussed in claims 34 and 35.

Regarding claim 56, Wu fails to disclose "biasing at least one of the first and second semiconductor devices toward the other of the first and second semiconductor devices." Lee shows biasing at least one of the first and second semiconductor devices toward the other of the first and second semiconductor devices (col. 4, lines 54-68). It would have been obvious to one of ordinary skill in the art at the time of the invention to incorporate the teaching of Lee into the device of Wu in order to have an electrical connection for a necessary circuit configuration of the device.

Regarding claim 57, Lee shows controlling the biasing by means of adhesive (col. 4, lines 54-68).

Regarding claim 58, Lee shows the controlling the biasing comprises controlling the biasing force to a level sufficient to deform, kink, bend, or collapse the discrete conductive elements.

See the respective portions of the specification such as col. 5, lines 24-32.

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Regarding claim 60, Wu fails to show "connecting the discrete conductive elements to corresponding contact areas of the substrate." Lee shows connecting the discrete conductive elements to corresponding contact areas of the substrate (col. 5, lines 8-10). It would have been obvious to one of ordinary skill in the art at the time of the invention to incorporate the teaching of Lee into the device of Wu in order to have current flow from supply contact areas of the substrate to the semiconductor devices through the discrete conductive elements (wires).

Claims 27, 32 and 48 are rejected under 35 U.S.C. 103(a) as being unpatentable under obviousness over Wu in view of Shim et al. (US 6,531,784), hereafter Shim.

Regarding claims 27 and 48, Wu does not disclose positioning a dielectric layer at least portions of the backside of the second semiconductor device. Fig. 7 of Shim shows the dielectric layer (50C) on the portion of the backside of the second semiconductor device. It would have been obvious to one of ordinary skill in the art at the time of the invention to incorporate the teaching of Shim into the device of Wu in order to enhance the electrical isolation between the devices and the wires.

Regarding claim 32, Wu does not disclose positioning a dielectric layer at least portions of the backside of the second semiconductor device. Fig. 3 of Shim shows the dielectric layer (44) on the portion of the backside of the second semiconductor device. It would have been obvious to one of ordinary skill in the art at the time of the invention to incorporate the teaching of Shim into the device of Wu in order to mount two devices securely.

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Response to Arguments

Applicant's arguments with respect to pending claims have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Junghwa M. Im whose telephone number is (703) 305-3998. The examiner can normally be reached on MON.-FRI. 8:30AM-5:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Eddie C Lee can be reached on (703) 308-1690. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 872-9318 for regular communications and (703) 872-9319 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

jmi
November 3, 2003



EDDIE LEE
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